



Attorney Docket: 2022/48819
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800

Group Art Unit: 1741

Filed: September 28, 2000

Examiner: W. Leader

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE MATERIAL
COATING OVER THE TOP SURFACE OF A PATTERNED SUBSTRATE AND
LAYER STRUCTURE MADE THEREBY

ADDITIONAL CLAIMS FEE CHART

Commissioner for Patents
Washington, D.C. 20231

Transmitted herewith is a Supplemental Reply for filing and
the filing fee is calculated below:

For	No. After Amendment	Highest No. Prev. Filed	No. Extra	Rate Fee
Total Claims	91	88	3	\$ 9/\$18 = \$54
Indep. Claims	14	14	0	\$40/\$80 = \$ 0
Multiple Dependent Claim Presented				\$135/\$270=\$ 0
TOTAL:				\$54

XX A check in the amount of \$54.00 is enclosed.

XX The Commissioner is hereby authorized to charge any additional
fees which may be required, or credit any overpayment, to Account
No. 05-1323 (Docket #2022/48819). A duplicate copy of this sheet
is attached.

November 13, 2002

Respectfully submitted,

Richard R. Diefendorf
Registration No. 32,390

CROWELL & MORING LLP
P.O. Box 14300
Washington, D.C. 20044-4300
Telephone No.: (202) 624-2500
Facsimile No.: (202) 628-8844
RRD:msy

RECEIVED
NOV 15 2002
TC 1700 MAIL ROOM



Attorney Docket: 2022/48819
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bulent M. Basol et al.

Serial No.: 09/671,800

Group Art Unit: 1741

Filed: September 28, 2000

Examiner: W. Leader

Title: PROCESS TO MINIMIZE AND/OR ELIMINATE CONDUCTIVE
MATERIAL COATING OVER THE TOP SURFACE OF A
PATTERNED SUBSTRATE AND LAYER STRUCTURE MADE
THEREBY

SUPPLEMENTAL REPLY

Commissioner for Patents
Washington, D.C. 20231

RECEIVED
NOV 15 2002
TC 1700 MAIL ROOM

Supplemental to the Reply filed November 12, 2002, electing the invention defined by claims 17-22, 58-60, 66, and 73-76 (invention II) for examination, kindly amend the claims of this application as follows.

Please cancel claims 20 and 60.

Please amend claims 17-19, 21, 58 and 59 as follows. A marked-up version of the amended claims is included at the end of this document.

11/14/2002 SSESHE1 00000015 09671800

01 FC:1202

54.00 OP

17. (Amended) A layer structure usable in manufacturing an integrated circuit made by a process comprising:

providing a patterned substrate,

supplying an electrolyte solution out of which a conductive material can be plated, under an applied potential, over a surface of said patterned substrate,